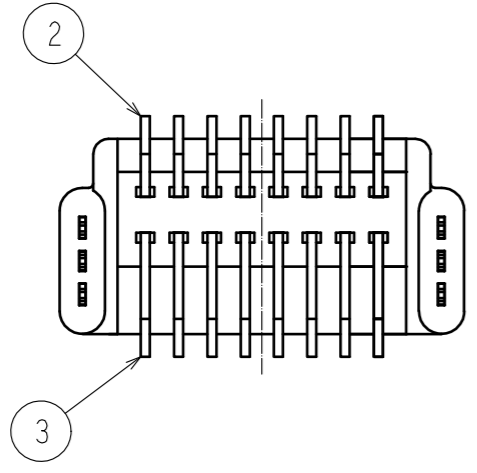
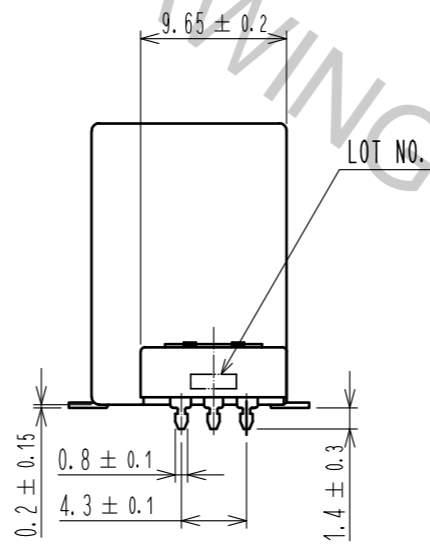
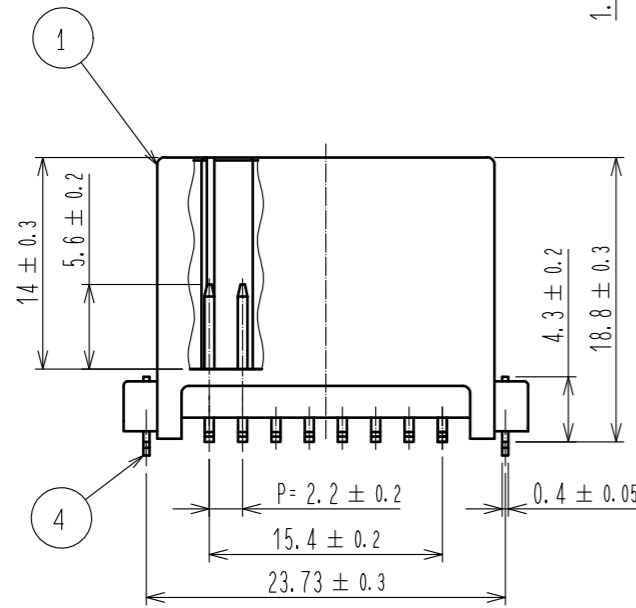
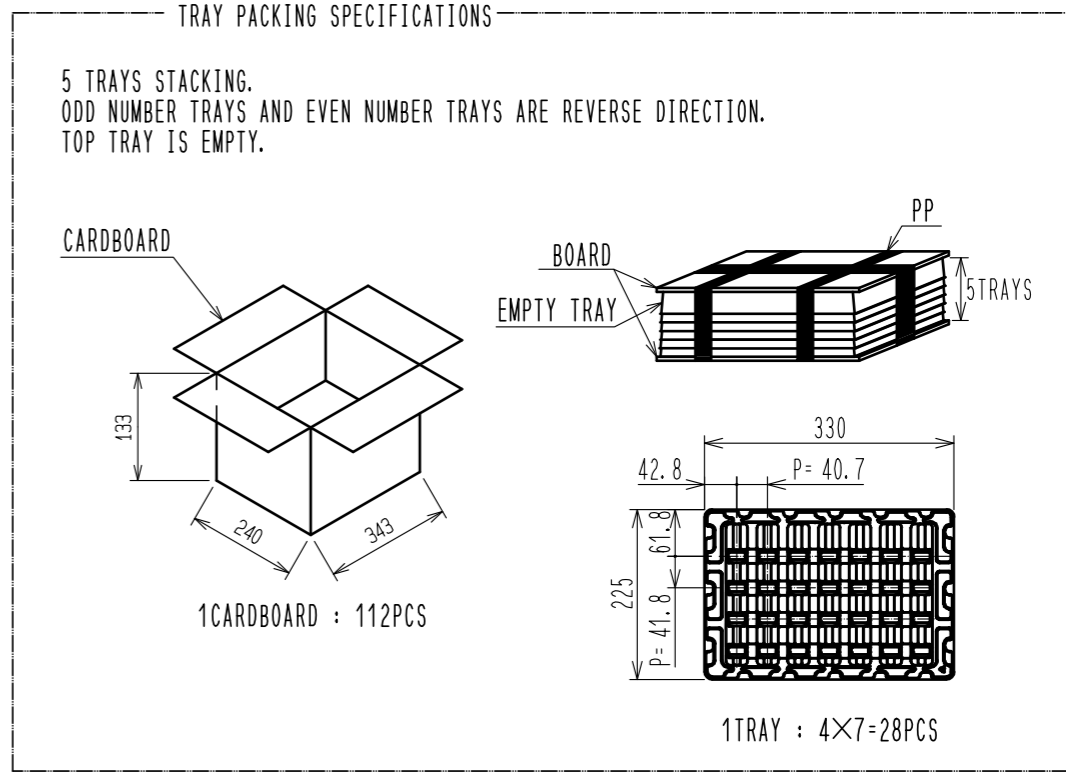
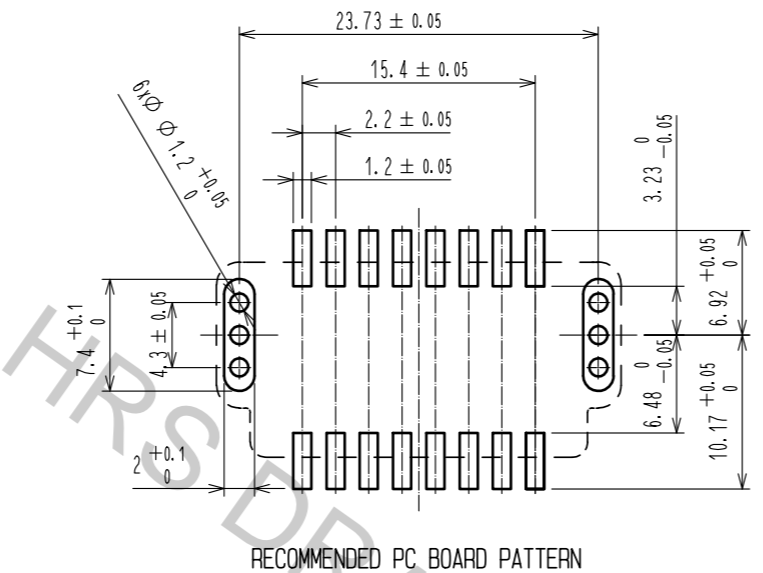
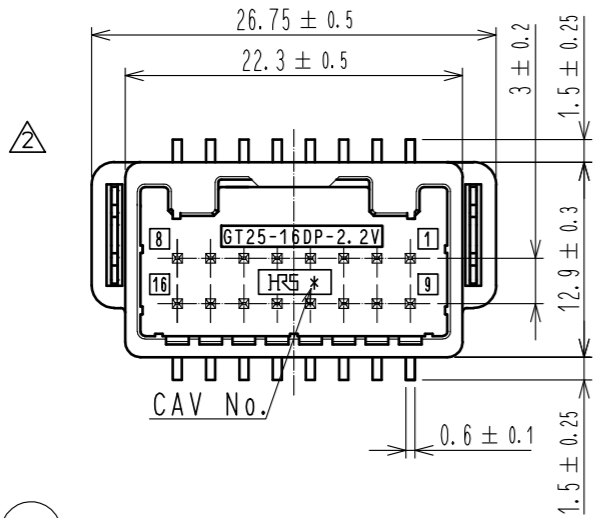
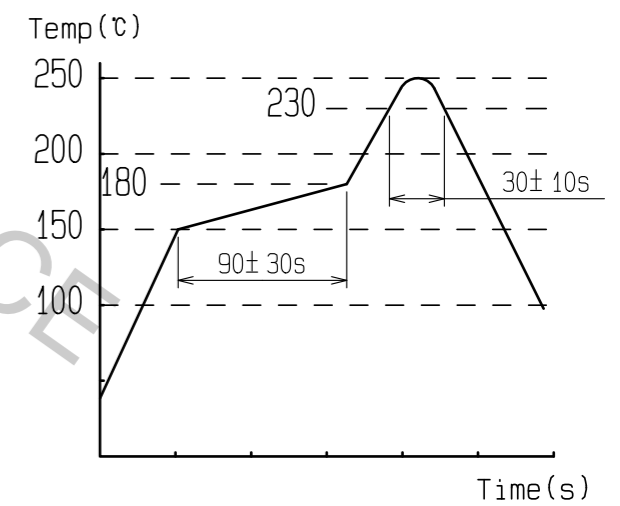


ELV, RoHS COMPLIANT



NOTE1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW  
(REFER TO RIGHT FIG.)  
USED REFLOW SYSTEM : IR IN THE AIR OR NITROGEN  
NO. OF CYCLES : 2 MAX  
PEAK : 250°C  
OVER 230°C : 20~40s  
PREHEAT : 150~180°C  
60~120s  
2. TEMPERATURE FOR SOLDERING IRON : 280~300°C WITHIN 2s  
3. CO-PLANARITY SHALL BE 0.1 MAX.  
4. PC BOARD THICKNESS=1.6.  
5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64	4	BRASS	TIN PLATED	T=0.4		
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	T=0.64		
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS		
UNITS	mm	SCALE	2 : 1	COUNT	1	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
						DIS-T-00000789	KT. MATSUDA	NH. NAKATA	16.01.06
<b>HRS</b> HIROSE ELECTRIC CO., LTD.		APPROVED	: TY. TAKAHASHI	12.07.26	DRAWING NO.		EDC3-166656-01		
		CHECKED	: TY. TAKAHASHI	12.07.26	PART NO.		GT25-16DP-2.2V(C01)		
		DESIGNED	: TY. SAKASHITA	12.07.26	CODE NO.		CL775-0020-8-01		
		DRAWN	: TY. SAKASHITA	12.07.26					